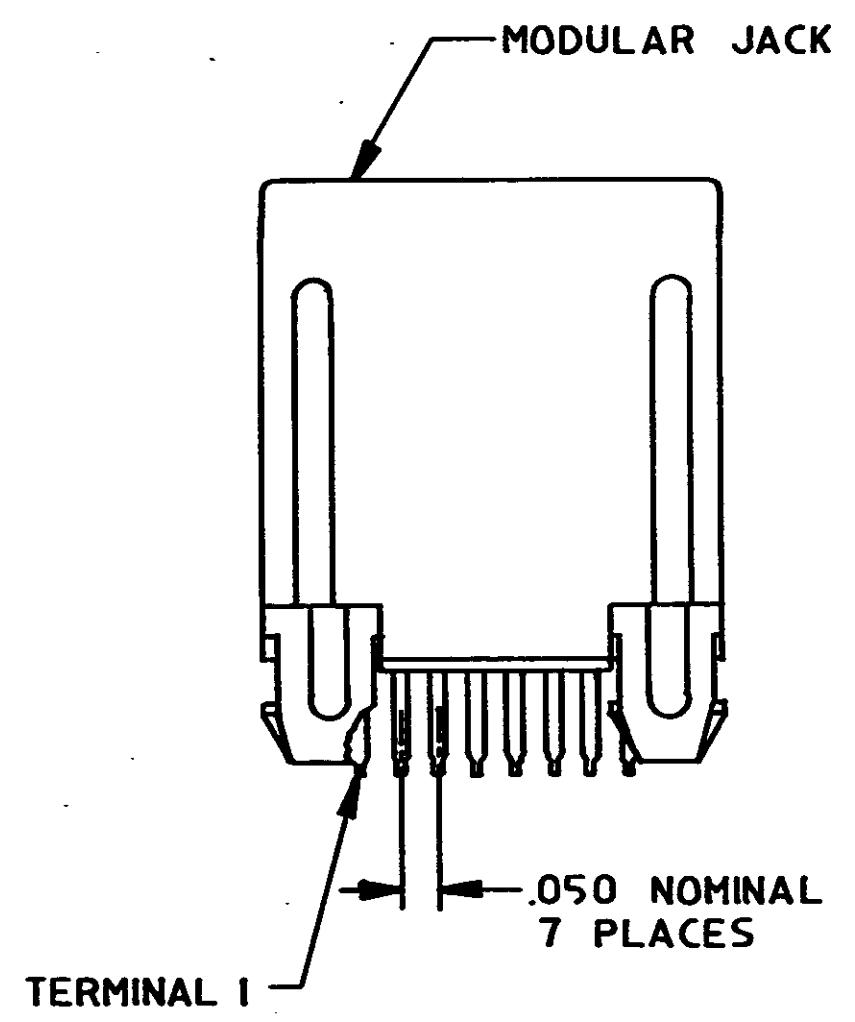
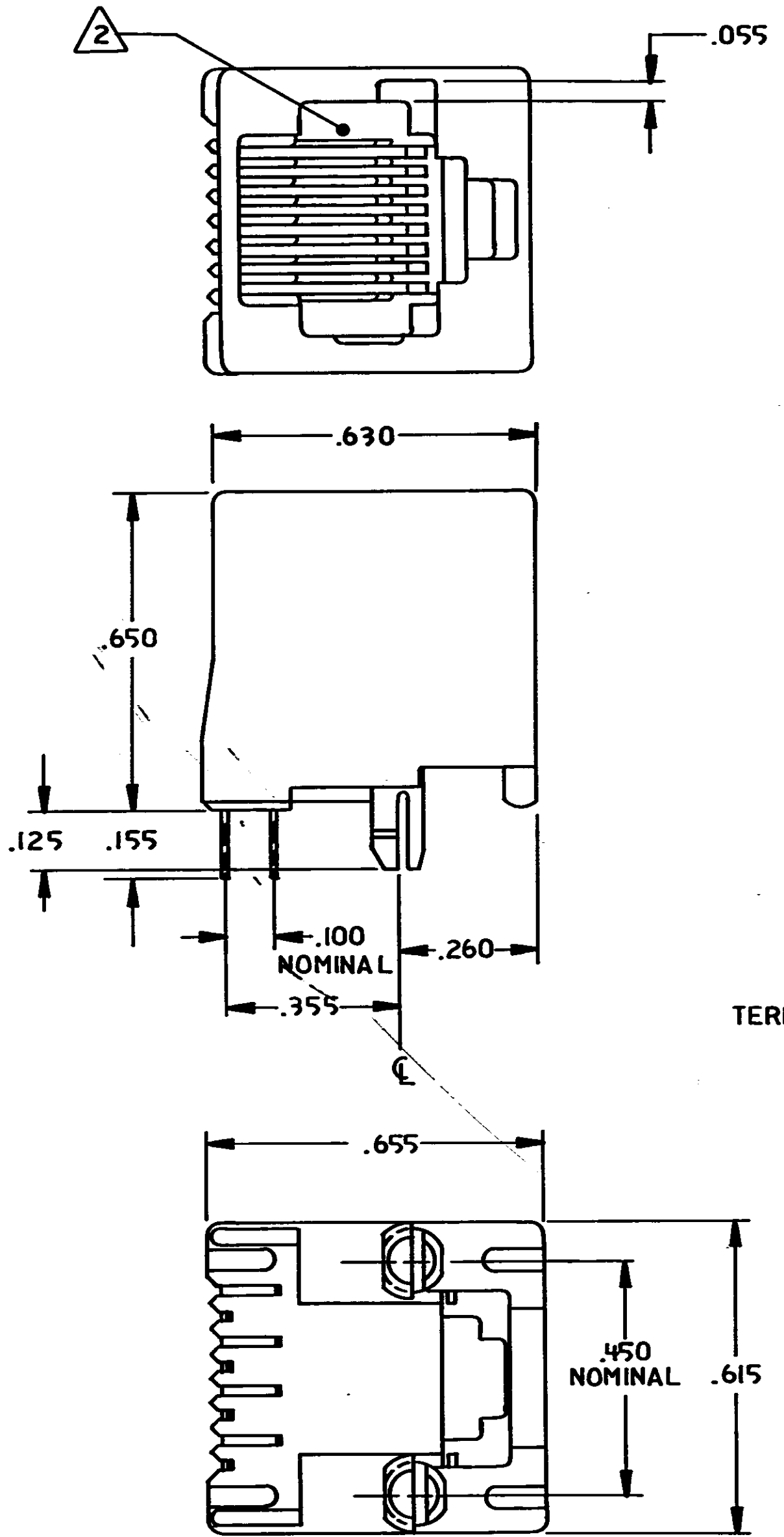


LOC	DIST	REVISIONS				DATE	APPD
AA	22	P	F	ZONE	LTR	DESCRIPTION	
						C REV: ECN 0210-10-93	3-22-93 DS



- 1 MATERIAL: HOUSING—PBT POLYESTER, BLACK. TERMINAL—.0138 THICK PHOS BRONZE PLATED WITH .000050 THICK HARD GOLD IN LOCALIZED GOLD PLATE AREA AND .000080 THICK TIN-LEAD IN SOLDER AREA OVER .000050 THICK NICKEL UNDERPLATE.
- 2 CAVITY CONFORMS TO FFC RULES AND REGULATIONS PART 68 AND REA BULLETIN 345-81, PE-76 SPECIFICATION FOR MODULAR TELEPHONE HARDWARE.
- 3. FOR APPLICATION INFORMATION SEE AMP SPECIFICATION 114-2048.
- 4. FOR PERFORMANCE REQUIREMENTS SEE AMP SPECIFICATION 108-1163.
- 5. ALL DIMENSIONS SHOWN ARE MAXIMUM UNLESS OTHERWISE SPECIFIED.

555799-1
PART NO

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES TOLERANCES ON		DR <i>DM WADDELL</i> 6-8-88		AMP AMP INCORPORATED Harrisburg, Pa. 17105	
2 PL DEC ±	—	CHK <i>Al. Clark</i> 6-13-88	NAME PRINTED CIRCUIT BOARD MODULAR JACK ASSEMBLY, TOP ENTRY, 8 POSITION, KEYED, FLANGELESS W/O PANEL STOPS		
3 PL DEC ±	—	APPD <i>Gene Reed</i> 6-14-88	SIZE	FSCM NO	DRAWING NO
ANGLES ±	—	APPD <i>D.B. Williams</i> 6-14-88	C	00779	555799
MATERIAL	1	PRODUCT SPEC	APPLICATION SPEC	SCALE 4:1	SHEET 1 OF 1
FINISH	1	WEIGHT			